Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.100”**

**.075”**

 **VIN VIN ENABLE GND**

**VOUT VOUT ADJUST**

**.MIC29150.AC**

**MASK**

**REF**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” X .004”**

**Backside Potential: GND**

**Mask Ref: MIC29150.AC**

**APPROVED BY: DK DIE SIZE .075” X .100” DATE: 2/21/23**

**MFG: MICREL/MICROCHIP THICKNESS .014” P/N: MIC29152**

**DG 10.1.2**

#### Rev B, 7/1